

May 2024

# **FAN41501 Ground Fault Interrupter Self-Test Digital Controller**

#### **Features**

- Meets 2015 UL943 Self-Test GFCI Requirement
- Internal 1-Second and 90-Minute Self-Test Timers
- Periodic Functional Testing for Key GFIC Components: GFCI Controller, Solenoid, Sense Transformer, and Silicon-Controlled Rectifier (SCR)
- Periodic EOL Testing without Compromising Normal GFCI Protection
- Built-in Noise Filters Reduce False EC ana.
- Automatic EOL Reset Capability
- Easily Added to Existing GF( Applica
- Built-in 5 V Shunt R Jula.or
- Energy-Saving Sys m Solu on
- Minimum kternal Co.
- Space Saving Sup SOT™ 6-Pin Packag

#### nlic: ions

- GrCl Ou put Receptable
- GFC! Circuit Breakers
- Portable GFCI Cords

# Description

tal untroller for periodic The FAN41501 is a k Ground Fault Circuit functional to ing Interrupte (G. 1) corponents In combination with an existing Fathild Controller, it periodically tests for peration of the GFCI controller, solenoid, nse transurmer SCR, and other discrete co non its without disrupting power to the load or com, amising normal GFC1 protection functionality. If the FAN/1501 detects a faulty GFCI component, it generates an End of Life (EOL) fault signal that can be used to deny power and/or automatically reset after the denial of power.

When the AC power is first applied, an internal timer starts a test cycle at one second. After this initial test cycle, the internal timer starts a test cycle every 90 minutes. During a test cycle, the FAN41501 simulates a ground fault and monitors the key GFCI components. If the FAN41501 detects a component fault, it verifies the ault several times to prevent a false EOL signal. At no time during a test cycle is the normal GFCI protection disabled or compromised.

The FAN41501 includes a 5 V shunt regulator, onesecond timer, 90-minute timer, digital control logic, detection comparators, and an EOL driver output.

The FAN41501, together with a GFCI controller such as FAN4149, provides a complete UL943 GFCI function with automatic monitoring capability, low system power, and a minimum number of external components.

The 6-pin, SuperSOT™ package enables a low-cost, compact design and layout.

# **Ordering Information**

Part Number	Operating Temperature Range	Package	Packing Method	
FAN41501SX	-35°C to +85°C	6-Lead, SuperSOT™, JEDEC M0-193, 1.6 mm	Tape and Reel	

# **Typical Application**

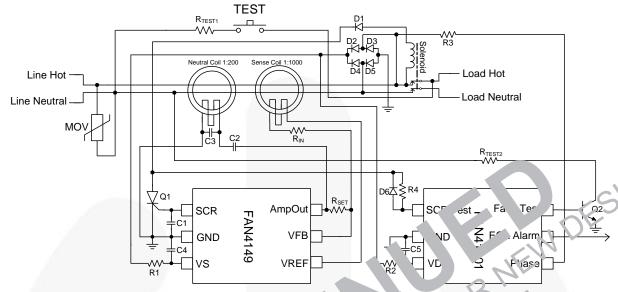


Figure 1. Typicai api. ati.

# Table 1. Typical Values (3)

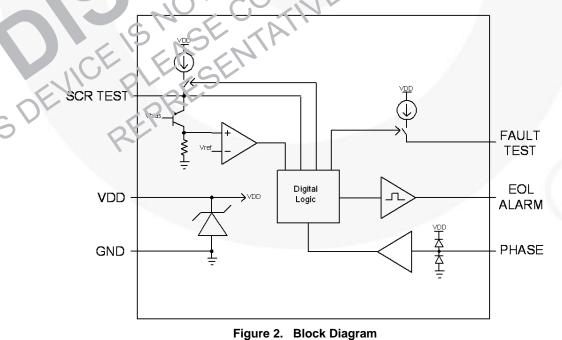
R4: 909 tΩ Re(12:)11 R<sub>3</sub> ¹ MΩ R1: 75 k $\Omega$ R2: 75  $k\Omega$ 

 $R_{SET}$ : 750  $k\Omega^{(4)}$ R<sub>IN</sub>: 470 Ω  $R_{Tes}$ , 15 k $\Omega$ 

C1: 22 nF C2: 10 n 3: 5.6 ni C5: 1 µF

#### Notes:

- Contact Fairchild S niconductor ... self-tos, requirement details.
- Portions of the actic as subject to U.S. paterns 8,005,516 and 8,760,824.
- XMFR: Mr ,netic Met. 50 J/F3006.
- nse coil characteristics and application. Value 1ep



# **Pin Configuration**



Figure 3. Pin Assignments

# **Pin Definitions**

1	Name	De rip on	
'	SCR Test	SCR test input for SCR functionalit	
2 GND Ground for FAN41501 circuitry		Ground for FAN41501 circuitry	
3	VDD	Voltage supply input for V4150 ircu y	
4	Phase	Phase input for V <sub>AC</sub> requent	
5	EOL Alarm	Alarm for end life s. hal	
6	Fault Test	Fault to tou igno ground-fault simulation	
0		RECONTACTOR INFO	

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Condition		Max.	Unit
Icc	Supply Current	Continuous Current, VDD to GND		10	mA
\/	Supply Voltage	Continuous Voltage, VDD to GND	-0.8	7.0	V
V <sub>CC</sub>		Continuous Voltage to Neutral, All Other Pins	-0.8	7.0	V
T <sub>STG</sub>	Storage Temperature Range			+150	°C
ESD	Electrostatic Discharge Capability	Human Body Model, ANSI / ESDA / JEDEC JS-001-2012		2.5	av.
		Charged Device Model, JESD22-C1		1.0	

# **Recommended Operating Conditions**

The Recommended Operating Conditions table definer the notions to actual device operation. Recommended operating conditions are specified to ensure optimal to a data sine specifications. Fairchild does not recommend exceeding them or designing to Absolute Malmum Kings. Unless otherwise specified, refer to Figure 1.  $T_A=25^{\circ}C$ ,  $I_{SHUNT}=1$  mA, and phase=60 Hz.

Symbol	Parameter	Conditions	Min.	7yp.	Max.	Unit
$V_{REG}$	Power Supply Shunt R gulator Voltage	DD to GND	5.10	5.35	5.70	V
V	Under-Voltaç Reset	YDD to GND	2.2	2.5	2.7	V
$V_{UVLO\_RST}$		Rising 'Avs'eresis		150		mV
ΙQ	Qu scer yre	ソロロ to GND 4.5 V	350	450	550	μA
t <sub>FIRST</sub>	'st Timer riod	V <sub>DD</sub> > 2.5 V	0.812	1.016	1.220	S
4PER	Pe dic ı mer	Stendy State	4400	5400	6400	S
тоит	est Cycle Tin e Out	Fault Testing	54	66	78	ms
t <sub>PHA</sub>	Phase Continuity Chock Time Out	Phase Pin Continuity Check at Startup	40	60	80	ms
V <sub>PHASE_H</sub>	Phase Voltage Clamp FIC'1	Ι <sub>Η</sub> = 170 μΑ	5.8	6.3	6.6	V
V PHASE_L	Phase Voltage Cla np LOW	I <sub>L</sub> = -170 μA	-0.8	-0.6	-0.4	V
PHASE_MAX	Phase Maximum Current	I <sub>SHUNT</sub> = 1.5 mA	-300		300	μΑ
V <sub>SCR_H</sub>	SCR Test Input Clamp HIGH	I <sub>H</sub> = 170 μA	5.0	5.4	5.8	V
V <sub>SCR_L</sub>	SCR Test Input Clamp LOW	I <sub>L</sub> = -170 μA	-0.8	-0.6	-0.4	V
I <sub>SCR_MAX</sub>	SCR Test Maximum Current	I <sub>SHUNT</sub> = 1.5 mA	-300		300	μΑ
I <sub>TEST</sub>	Fault Test Current	Test Cycle	400	500		μΑ
$V_{EOL\_L}$	EOL Alarm V <sub>OL</sub>	DL Alarm V <sub>OL</sub> No Load		0	200	mV
$V_{EOL_H}$	EOL Alarm V <sub>OH</sub>	No Load	4.80	5.25		V
f <sub>EOL</sub>	EOL Alarm	Latched Fault Output	3.00	3.75	4.25	Hz
I <sub>EOL</sub>	EOL Alarm I <sub>OUT</sub>	I <sub>SHUNT</sub> = 2.0 mA	1		_	mA

# **Functional Description**

(Refer to Figure 1)

Starting in June 2015, UL943 will require all permanently connected GFCI products to perform a self test function. The FAN41501, together with a GFI controller device – like the FAN4149 – provides GFI fault protection and periodic self testing of the key GFCI components: solenoid, SCR, GFI controller, sense coil, and other discrete components.

The FAN41501 has an internal 5.35 V shunt regulator. With diodes D2-5 and resistor R2, the shunt regulator clamps the FAN41501  $V_{DD}$  supply voltage to 5.35 V. Capacitor C5 provides bias during the V<sub>AC</sub> zero phase crossing so the FAN41501 is continuously biased. When power is first applied, an internal Power-On-Reset (POR) circuit detects when V<sub>DD</sub> is greater than 2.5 V. The POR circuit generates an internal reset pulse and initializes a one-second timer. After one second, the first self-test cycle starts. During the positive half cycle when the "line-hot" voltage is positive with respect to the "lineneutral" voltage, the SCR anode voltage is monitored by means of resistor R4 connected to pin 1 (SCR Test). The FAN41501 clamps this pin to VDD, mirrors the current through R4 to an internal low-pass filter ci all and compares its value to an internal re rence threshold. When the current level exceeds the refunce threshold, an internal latch is set. This tes. . the continuity of the solenoid and The thres. J level is determined by:

$$Vth_{rms} = (65 \mu A \times R) \qquad (1)$$

where  $Vth_{rm}$  is the ms  $V_{AC}$  iput voltage with a tolerance  $t \pm t 0\%$ .

With the commende application values the SCR anode voltal must be seed a whist-case peak voltage of uppromations of control of the seed in a line with shell a voltage value is obtained to allow this test a particular of the province of voltage sages of dition.

To tex the functionality of the GFCI convoller, sense coil, and SCR; a simulated ground fault condition is generaled. Like the SCR Test pin, the Phase pin (pin 4) is clarged to V<sub>DD</sub> + 700 mV, mirrors the current through k3 .o an internal low-pass filter circuit, and compares its value to an internal reference. This internal circuit detects when the phase signal is near the end of the positive half cycle. When this occurs, an internal current source is enabled to bias the SCR Test pin. This prevents the SCR anode voltage from discharging to zero during the negative half cycle since it is reversebiased by diode D1. At the end of the positive half cycle. the FAN41501 generates a current pulse for the Fault Test pin (pin 6). This current pulse enables transistor Q2, which biases the collector voltage of Q2 to a low voltage. During the negative half cycle when the lineneutral voltage is positive with respect to the line-hot voltage, current flows through resistor R<sub>TEST2</sub> when Q2 is enabled. This current creates a simulated ground fault from line-neutral to load hot. This current is detected by

the GFI controller (i.e. FAN4149) and, when it exceeds the programmed trip threshold set by R<sub>SET</sub> (typically 5 mA<sub>rms</sub>), the controller enables the SCR Q1 (see FAN4149 datasheet for I<sub>FAULT</sub> trip threshold equation). The SCR quickly discharges the anode voltage, which is pre-biased by the FAN41501 control logic. The discharge of the anode voltage also biases the voltage at the SCR Test pin to a low voltage by forward-biasing diode D6. The FAN41501 monitors the SCR Test pin during this test cycle and sets a latch if the SCR is triggered. The simulated ground fault tests for the functionality of the controller, R1, D1 D2-5<sup>(5)</sup>, sense coil, and SCR without opening the lace acts. The load contacts do not open during a test cause D1 is reversed biased, which reverse to rent to menergizing the solenoid. Once the ANA 01 c is the triggering of the SCR, the culint per for O2 is disabled and the bias current for pin R. At i emoved. This disables the SCR so it during the next positive half cycle the no ener zed. With the recommended solenoid tion blue a simulated ground fault triggers ap; with a VAC input voltage greater than `e t V<sub>rms</sub> If a unrerent voltage threshold is required, the R<sub>TL 2</sub> sistor can be adjust to (per the FAN4149 data eet). Figure 4, Figure 5 and Figure 6 show a passing selitest cycle. The wavelown of channel 4 shows when the C2 transistor is enabled and a ground fault is simulated by the current through resistor R<sub>TEST2</sub>. The channel 3 waveform shows the gate of the SCR Q1. Figure 3 shows the pre-bias for the SCR anode voltage, waveforing thannel 1. Figure 6 illustrates that, when the gate of the SCR is enabled by the controller, the voltage of the SCR anode is quickly discharged. The FAN41501 detects this and a self-test cycle is completed with all of the required components passing. The Q2 bias is disabled, which causes the GFCI controller to disable the SCR gate bias.

#### Note:

5. Redundant diodes may be required.

If the first self-test cycle passes after power up, subsequent self-test cycles occur every 90 minutes. At no time does the FAN41501 disable the normal controller GFI protection circuitry.

If any one of the above self tests fail, the FAN41501 repeats the self testing until a 66 ms timer expires. If this occurs, the EOL latch is enabled and the FAN41501 EOL Alarm pin 5 goes HIGH. This signal can be connected to a separate SCR or to the gate of Q1 with a series diode. When the EOL Alarm goes HIGH, the SCR is enabled and energizes the solenoid, which opens the load contacts. When the EOL Alarm pin goes HIGH, if it is connected to the gate of an SCR, VDD drops below 2.5 V. This generates a Power-On-Reset that resets the logic and repeats a self-test cycle in one second. Figure 7 to Figure 10 show a FAN41501 self-test cycle for a SCR, GFI controller, sense coil, and solenoid failure.

The self test cycle lasts for 66 ms to allow four self-test cycle attempts. After the timer has expired, the EOL alarm is enabled. Figure 7 to Figure 10 show an example of the EOL alarm signal connected to the gate of an SCR. When the EOL alarm signal is enabled, the  $V_{DD}$  voltage is discharged, which causes a POR. The EOL alarm is disabled and a self-test cycle is repeated in one second.

In addition to the above GFCI tests, the FAN41501 also performs a pin 4 (Phase pin) continuity check when power is first detected. When  $V_{DD}$  exceeds 2.5 V, pin 4 is checked for an open or short. If this continuity check fails after 60 ms, the EOL alarm is enabled. Figure 11 shows an example of the Phase pin with R3 removed (floating pin). After approximately 60ms, the EOL alarm is enabled.

After a self-test cycle failure, the EOL alarm is latched HIGH for 133 ms. This signal generates a repetitive 3.75 Hz digital square wave. There are two ways to reset the EOL alarm signal. The first is POR as described above, which can occur if the AC power is cycled. Since it may be undesirable to cycle the AC power, the EOL alarm signal can also be connected to the gate of a SCR or "clamp diode" to generate a PO" If the EOL alarm signal is diode clamped when the LOL alarm signal goes HIGH, a high I<sub>OH</sub> current is generated. This current is dependent on R2 and C5, herever, the datasheet values are used, the typical I<sub>OH</sub>, ... can be greater than 5 mA. This given can be used to "latch on" a SCR and ca se V<sub>DD</sub> dr below 2.5 V, which generates a POP Figure 11 s ows the Vpp signal when the EOL at an signal conjected to the gate of a SCR with a sc es diodo. The nigh EOL alarm. IOH current caus 'DD drop slow 2.5 / during the DEVICE PLEASENTAT V<sub>AC</sub> zero cross ig.

Another way to reset the EOL alarm signal is to detect a successful manual test cycle. If the FAN41501 is latched in an EOL state and detects a "manual test" (i.e., the TEST button is pressed) the FAN41501 disables the EOL alarm and perform sa self-test cycle in one second. If an EOL alarm state has occurred due to a pin 4 continuity check failure, the "manual test" reset option is disabled.

Referring to Figure 1, the EOL alarm signal must be used to open the load contacts (power denial) if a selftest cycle fails for the tested components (with the exception for a solenoid or SCR open failure). As described above, this can be done with a redundant SCR or by connecting the EOL 2' and nal to Q1 via a series diode. If Q1 is used to o, n the id contacts, a gate resistor must be ad a fro. the CCI controller gate drive pin to the ate of the CC. If O1 or the solenoid fails due 'an circuit, a visual FO signal can be generated in leach find an denial. This can be accomplished y mak in the Jeries alook from the EOL Alarm pin o to gate f Q1 a LEO diode. This diode flas' eve sec additionally, an LED diode can be dde 11. with R<sub>TE sT2</sub> and the corlector of Q2. This L D a de ca., be used to provide a self-test signal at point and then every 90 conutes. If the self-test cycle ails, it flashes every sound.

n summary, the FAN415'1 can be added to an existing UL943 choult to comply with the 2015 UL self-test requirement. The small package size and the minimum required components allow for a compact, low-cost, GFC' self-test solution.

Cortact a Farchild Semiconductor representative for details about how to test the FAN41501 self-test features in production or for details about the 2015 UL943 self-test application requirements.

# **Typical Performance Characteristics**

Pass testing of all key components. Refer to evaluation board (see www.fairchildsemi.com for details).

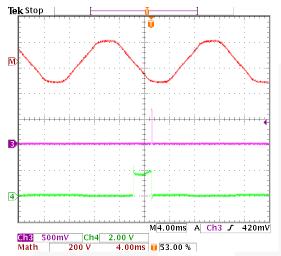


Figure 4. Pass GFCI, Sense Coil, Solenoid, SCR Tests; Ch Math: V<sub>AC</sub> Input 200 V/Div, Ch3: SCR Gate, Ch4: Fault Test (Pin 6)<sup>(6)</sup>

Figure Parts in lated Ground Fault Test;

Vac input 200 V/Div, Ch3: SCR Gate,
Ch4: Fault Test (Pin t)

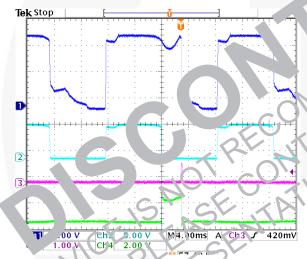


Figure 8. Pass Simulated Ground Fault Test; th1: SCR Test (Pin 1) Ch2: Phase (Pin 4), Ch3: SCR Gate, Ch4: Fault Test (Pin 6)<sup>(7)</sup>

#### Notes:

- 6. Anode voltage is tested during the positive half cycle (internal latch set when  $V_{AC} > 85 V_{rms}$ ).
- 7. During the simulated ground fault test, the SCR discharges the pre-biased SCR Test pin.

### **Ground Fault Tests**

SCR, GFI, sense coil, and solenoid failures.

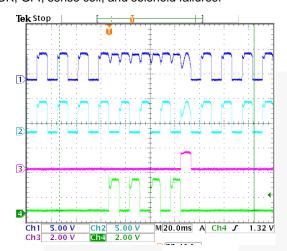
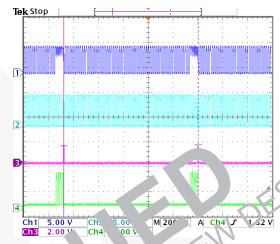


Figure 7. SCR Test Ch1: SCR Test (Pin 1), Ch 2: Phase (Pin 4), Ch 3: EOL Alarm (Pin 5), Ch 4: Fault Test (Pin 6)<sup>(8)</sup>



Figu 8. CR To t Ch1: SCR Test (Pin 1); Ch2. 'hao (Pi 4); Ch3: FOL Alarm (Pin 5), Cha. Fault Test (Pin 6)<sup>(9)</sup>



Fur .. GFiri Sense Coi Tests Ch1: SCR Anode ...00 V/div). Ch2: Phase (Fin 4). Ch3: EOL Alarm (Pin 5), Ch4: Fault Test (Fin 6)<sup>(10)</sup>

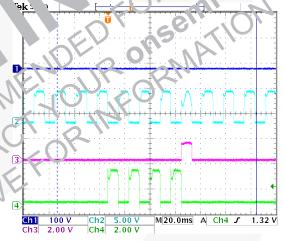


Figure 10. Solenoid Test Ch1: SCR Anode (100 V/Div), Ch2: Phase (Pin 4), Ch3: EOL Alarm (Pin 5), Ch4: Fault Test (Pin 6)<sup>(11)</sup>

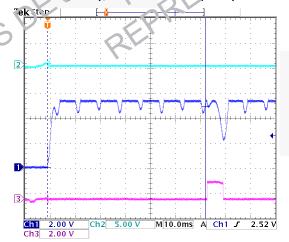


Figure 11. Phase Pin, Continuity Test; Ch1: VDD (Pin 3), Ch2: Phase (Pin 4), Ch3: EOL Alarm (Pin 5)<sup>(12,13)</sup>

#### Notes:

- This test is with the SCR disabled. The EOL alarm signal is enabled after "time out" 66 ms timer has expired. The EOL alarm signal is connected to the gate of a SCR.
- This test is the same as Figure 7, except for the time scale. After a self-test failure, an EOL alarm pulse is generated every one second.
- 10. This test is with the FAN4149 GFI controller disabled.
- 11. This test is with the solenoid open.
- 12. This test is with the Phase pin open.
- 13. If no signal is detected for the Phase pin within 60 ms of the POR, an EOL alarm is enabled. The SCR is enabled, which causes the V<sub>DD</sub> voltage to drop and generates a POR cycle.

# **Typical Temperature Characteristics**

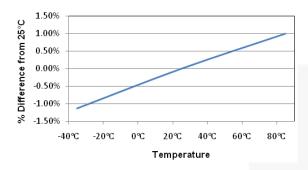
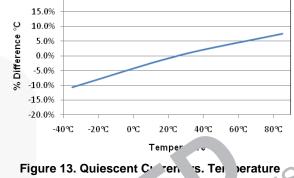


Figure 12. Shunt Regulator Voltage vs. Temperature



20.0%

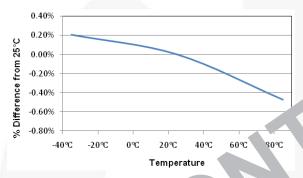


Figure 14. Under-Voltage Res .. Ten gratu.

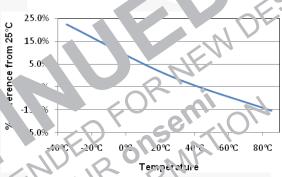
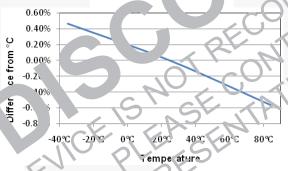


Figure 15. Phase Pin Continuity Check Time vs. Temperature



กัญนาย 16. Phase Pin Volage Clamp High vs. ∫e. nperature

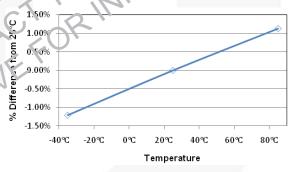


Figure 17. SCR Test Pin Voltage Clamp High vs. Temperature

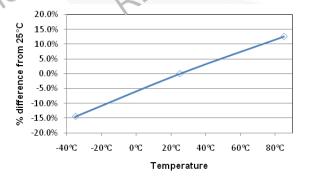


Figure 18. Fault Test Pin Current vs. Temperature

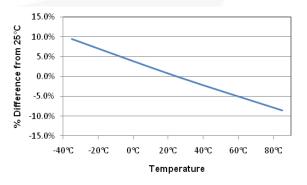


Figure 19. EOL Alarm Pin I<sub>OUT</sub> vs. Temperature

# **Physical Dimensions** SYMM E 0.95 -0.951.00 6 В 3.00 2.60 1.70 1.50 3 0.50 0.30 0.95 ◆ 0.20 M A B 1.90 RECOMME (0.30)-1.00 0.70 0.20 0.08 0.1 NOTES: UNLESS OTHERWISE SPECIFIED THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000. ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 0.55 0.35 SEATING PLANE -0.60 REF DETAIL A

Figure 20. 6-Lead, SuperSOT™-6, JEDEC M0-193, 1.6 mm

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